ASYNC 2007 Call for Papers

March 12–14, 2007 — Berkeley, California, USA
Venue: University of California at Berkeley

The 13th IEEE International Symposium on Asynchronous Circuits and Systems

The International Symposium on Asynchronous Circuits and Systems provides a high-quality forum for scientists and engineers to present their latest research findings. Authors are invited to submit full papers on all aspects of asynchronous design. Topics of interest include, but are not limited to:

- Mixed synchronous/asynchronous architectures, interfaces, and circuits.
- High-speed/low-power asynchronous logic, memories, and interconnects.
- High-level design and synthesis of self-timed circuits.
- Physical design of unclocked logic and pipelines.
- Formal methods for correctness and performance analysis of asynchronous designs.
- Test, reliability, security, and radiation tolerance.
- CAD for asynchronous design and validation.
- Asynchronous System-on-Chip (SoC), System-in-Package (SiP), and Network-on-Chip (NoC).
- Novel asynchronous architectures.
- Asynchrony and latency tolerance in system-level design.

Papers should be submitted via the conference web site. The submission should not exceed ten pages in IEEE double-column format. Papers that exceed the length limit may not be reviewed. Papers will be evaluated by the program committee and reviews will be based on scientific merit, innovation, relevance, and presentation. New-idea papers are encouraged, and the program committee recognizes that such papers may contain less evaluation than papers in established areas. Accepted papers will be published in an IEEE proceedings and distributed at the symposium. Please check the symposium website for up-to-date information:

http://conferences.computer.org/async2007

Paper Schedule:
- Submission deadline (note new dates):
  - Title + author info + abstract: September 25, 2006
  - Full paper: October 2, 2006 (firm)
- All deadlines are 11:59pm Pacific Time [GMT-7]
- Notification of acceptance: November 20, 2006
- Final version due: December 20, 2006

*IEEE sponsorship pending